



Transformers

DC/DC converters
ER 11

Ordering code: **B78334B1018A003**

Date: **October 2012**

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Construction

- ER 11 ferrite core with 10 gullwing terminals

Features

- RoHS-compatible

Applications

- Pulse transformers
- Drive transformers for power semiconductors (full bridge)

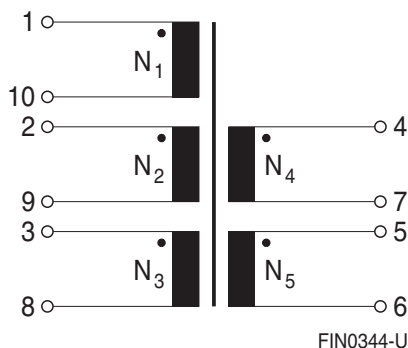
Marking

- Manufacturer, middle block of ordering code, date code, pin1 marker

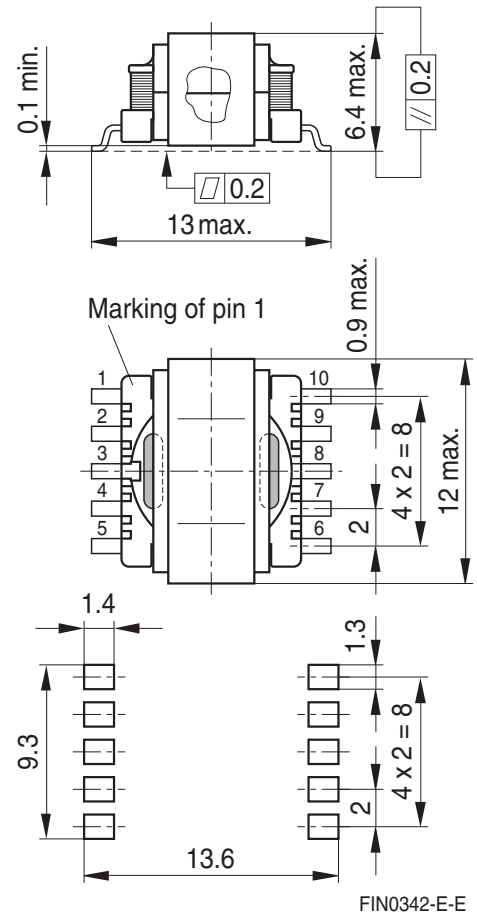
Delivery mode and packing unit

- 24-mm blister tape, reel 330 mm
- Packing unit: 600 pcs./reel

Pinning



Dimensional drawing



Technical data and measuring conditions

Main inductance L (1-10)	10 kHz, 10 mV
Test voltage V_{test}	50 Hz, 1 s
Operating temperature range	-40 °C ... +85 °C
Weight	Approx. 1.5 g

Characteristics and ordering code

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Type/Core	ER 11	
$N_1 : N_2 : N_3 : N_4 : N_5$	0.382 : 1 : 1 : 1 : 1	
L	288.3 +40/-30%	μH
V_{test}	1200	V AC

Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule we are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether a product with the properties described in the product specification is suitable for use in a particular customer application.
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